

N-Channel Power MOSFET

600V, 24A, 165mΩ

FEATURES

- Low $R_{DS(ON)}$ to minimize conductive losses
- Low gate charge for fast power switching
- 100% UIS and R_g tested
- ROHS Compliant
- Halogen-free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS

PARAMETER	VALUE	UNIT
V_{DS}	600	V
$R_{DS(on)}(\text{max})$	165	mΩ
Q_g	47	nC

APPLICATIONS

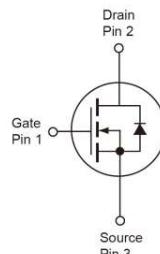
- PFC Stage
- Power Supply
- AC/DC LED Lighting



ROHS
COMPLIANT

HALOGEN
FREE

ITO-220



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current (^{Note 1})	I_D	24	A
$T_C = 100^\circ\text{C}$		15	A
Pulsed Drain Current (^{Note 2})	I_{DM}	72	A
Total Power Dissipation @ $T_C = 25^\circ\text{C}$	P_D	89	W
Single Pulse Avalanche Energy (^{Note 3})	E_{AS}	450	mJ
Single Pulse Avalanche Current (^{Note 3})	I_{AS}	4.2	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Case Thermal Resistance	R_{eJC}	1.4	°C/W
Junction to Ambient Thermal Resistance	R_{eJA}	60	°C/W

Thermal Performance Note: R_{eJA} is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. R_{eJA} is guaranteed by design while R_{eCA} is determined by the user's board design.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ C$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static <small>(Note 4)</small>						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV_{DSS}	600	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(TH)}$	3	3.8	5	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	I_{DSS}	--	--	100	μA
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 5A$	$R_{DS(on)}$	--	143	165	$m\Omega$
Dynamic <small>(Note 5)</small>						
Total Gate Charge	$V_{DS} = 480V, I_D = 15A, V_{GS} = 10V$	Q_g	--	47	--	nC
Gate-Source Charge		Q_{gs}	--	12	--	
Gate-Drain Charge		Q_{gd}	--	20	--	
Input Capacitance	$V_{DS} = 300V, V_{GS} = 0V, f = 1.0MHz$	C_{iss}	--	1857	--	pF
Output Capacitance		C_{oss}	--	53	--	
Reverse Transfer Capacitance		C_{rss}	--	10	--	
Gate Resistance	$f = 1.0MHz$	R_g	--	1.6	3.2	Ω
Switching <small>(Note 6)</small>						
Turn-On Delay Time	$V_{DD} = 300V, R_G = 10\Omega, I_D = 15A, V_{GS} = 10V$	$t_{d(on)}$	--	30	--	ns
Turn-On Rise Time		t_r	--	50	--	
Turn-Off Delay Time		$t_{d(off)}$	--	60	--	
Turn-Off Fall Time		t_f	--	12	--	
Source-Drain Diode <small>(Note 4)</small>						
Body-Diode Continuous Forward Current		I_s	--	--	15	A
Body-Diode Pulsed Current		I_{SM}	--	--	60	A
Forward Voltage	$I_s = 15A, V_{GS} = 0V$	V_{SD}	--	0.8	1.6	V
Reverse Recovery Time	$I_s = 7.5A$ $dI_F/dt = 100A/\mu s$	t_{rr}	--	327	--	ns
Reverse Recovery Charge		Q_{rr}	--	4.8	--	μC

Notes:

1. Current limited by package.
2. Pulse width limited by the maximum junction temperature.
3. $L = 50mH, I_{AS} = 4.2A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^\circ C$
4. Pulse test: $PW \leq 300\mu s$, duty cycle $\leq 2\%$.
5. For DESIGN AID ONLY, not subject to production testing.
6. Switching time is essentially independent of operating temperature.

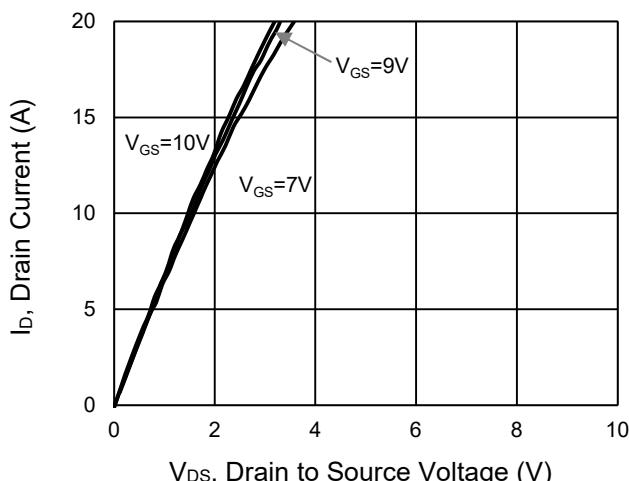
ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM60NC165CI C0G	ITO-220	50pcs / Tube

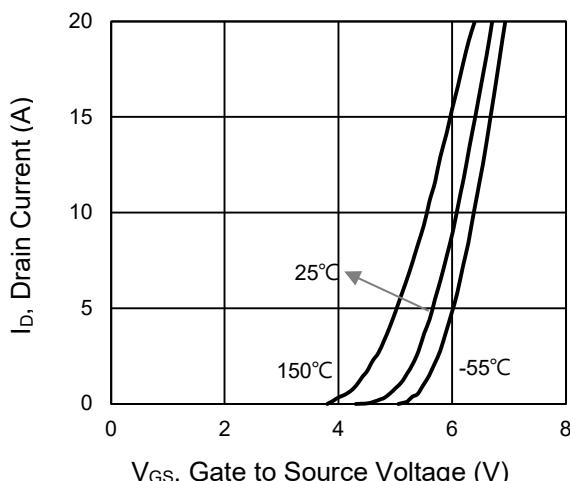
CHARACTERISTICS CURVES

($T_c = 25^\circ\text{C}$ unless otherwise noted)

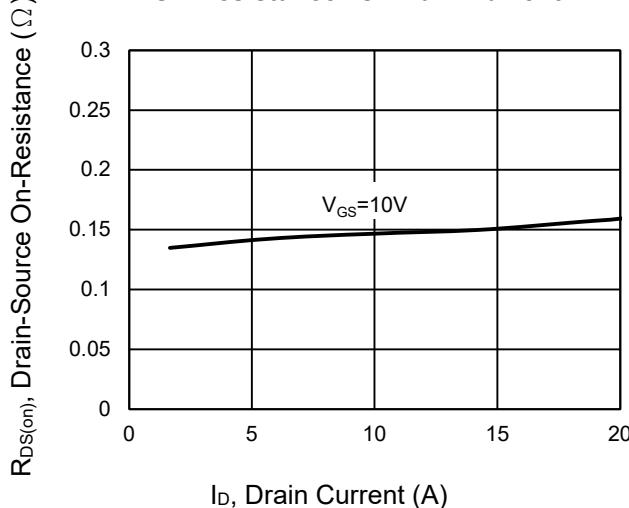
Output Characteristics



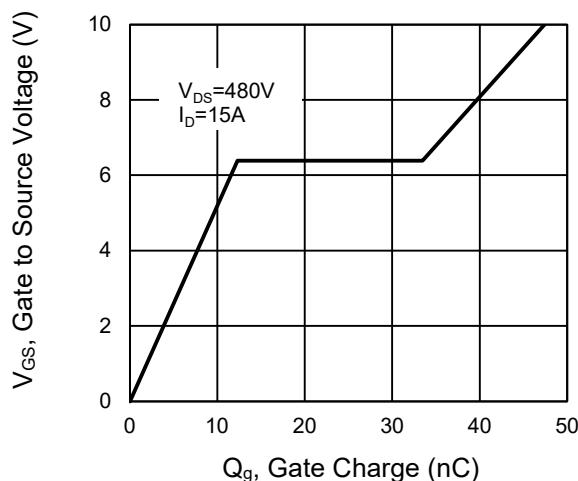
Transfer Characteristics



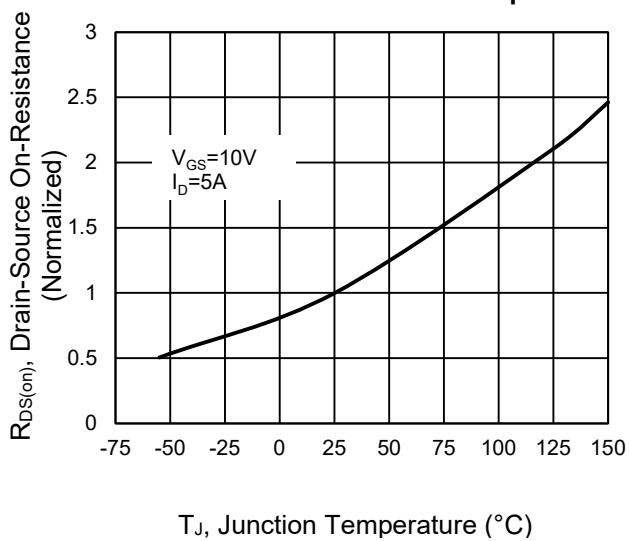
On-Resistance vs. Drain Current



Gate-Source Voltage vs. Gate Charge

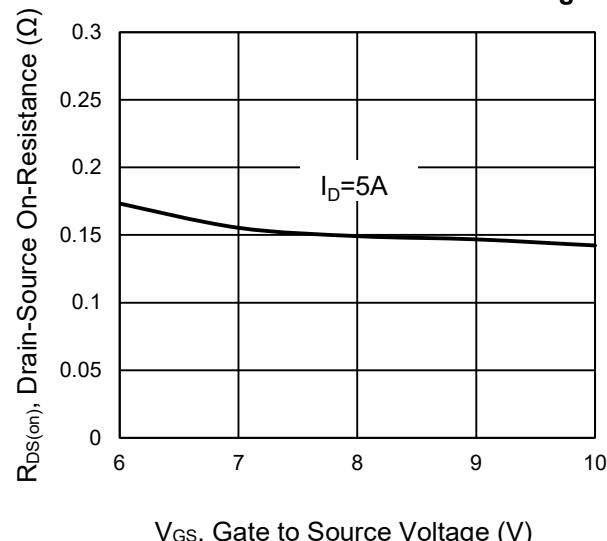


On-Resistance vs. Junction Temperature



T_J , Junction Temperature (°C)

On-Resistance vs. Gate-Source Voltage

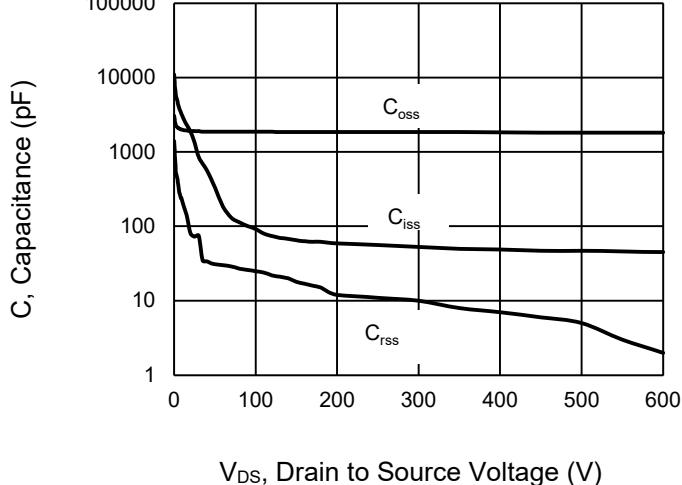


V_{GS} , Gate-to-Source Voltage (V)

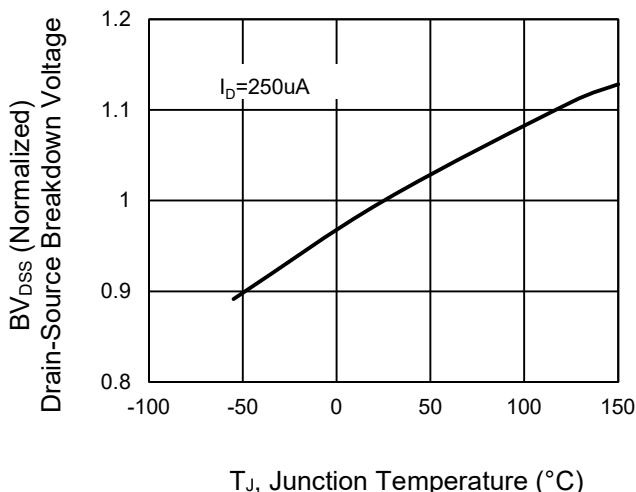
CHARACTERISTICS CURVES

($T_c = 25^\circ\text{C}$ unless otherwise noted)

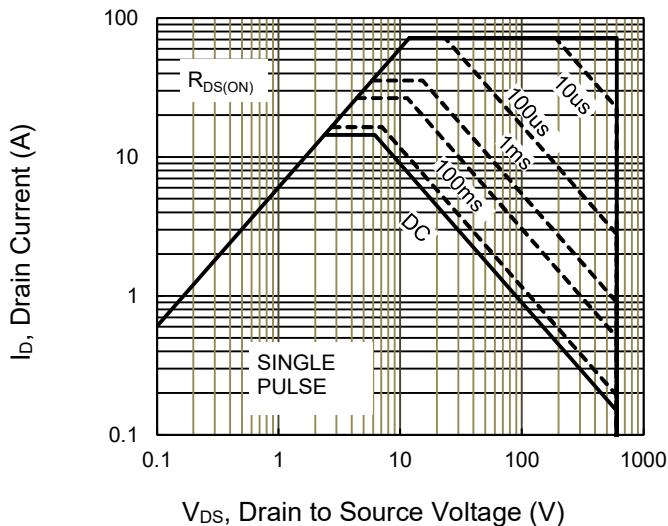
Capacitance vs. Drain-Source Voltage



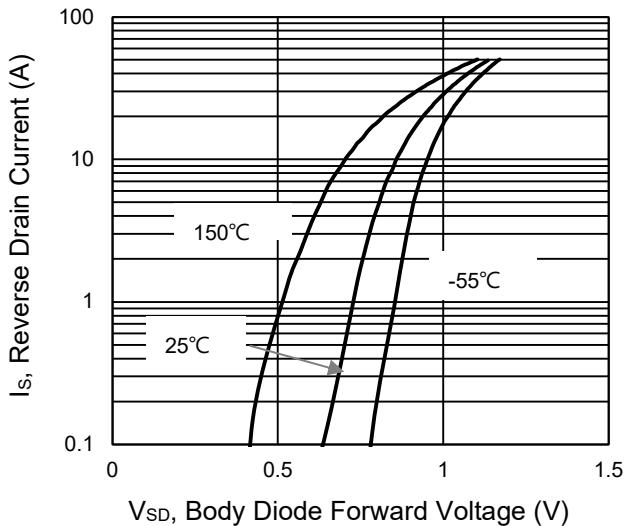
BV_{DSS} vs. Junction Temperature



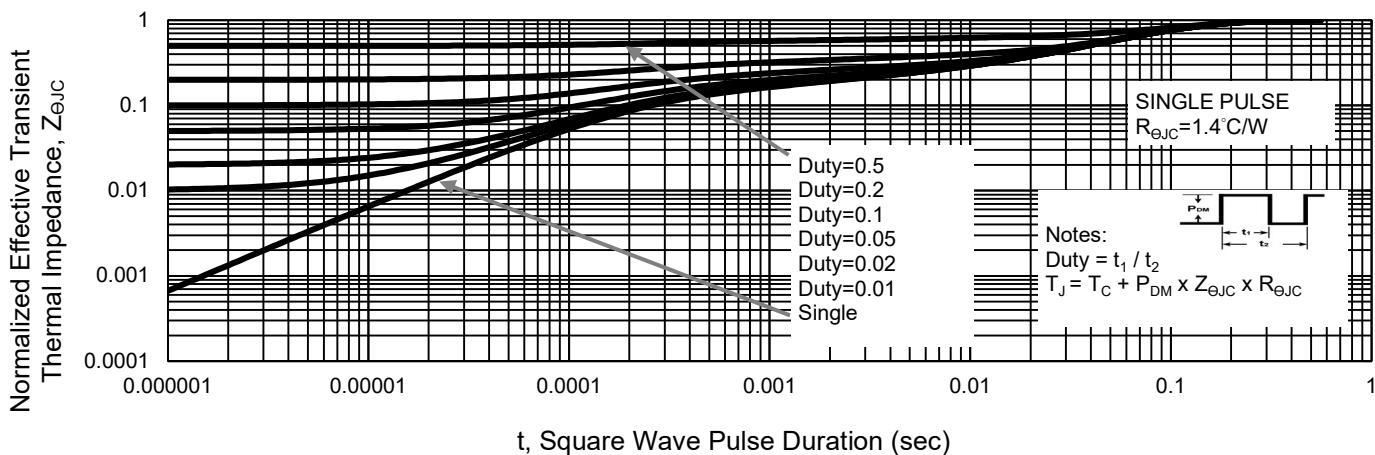
Maximum Safe Operating Area, Junction-to-Case

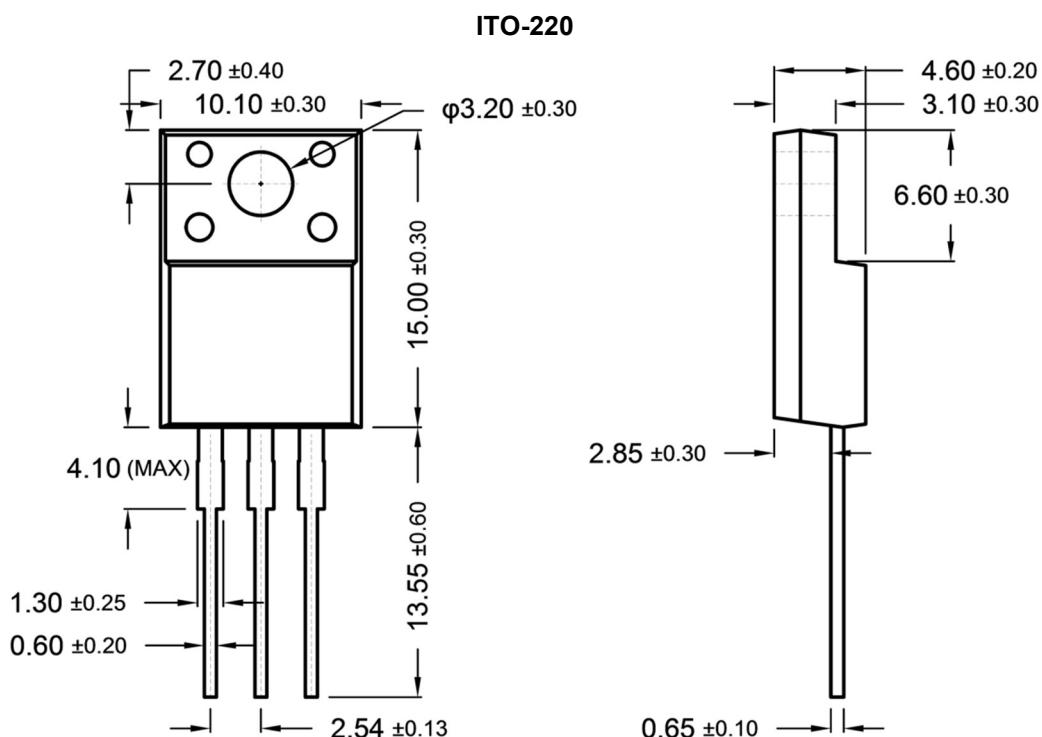
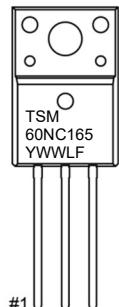


Source-Drain Diode Forward Current vs. Voltage



Normalized Thermal Transient Impedance, Junction-to-Case



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

MARKING DIAGRAM


Y = Year Code
WW = Week Code (01~52)
L = Lot Code (1~9,A~Z)
F = Factory Code

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